



Welcome to **E-XFL.COM** 

# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	41984000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-FBGA (40x40)
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxeb5r2f40c2l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Page 2 Electrical Characteristics

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes <sup>(4)</sup>	Yes

#### Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Crad Crado	Core Speed Grade							
Transceiver Speed Grade	C1	C2	12	13				
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_				
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes				

#### Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

### **Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	-0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	-0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	-0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	-0.5	3.9	V

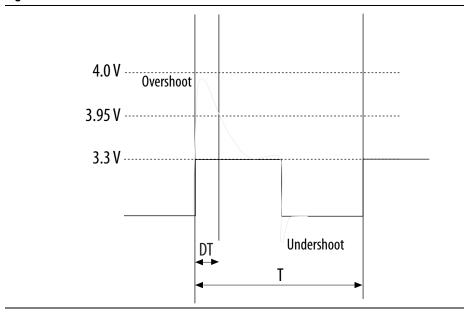
Page 4 Electrical Characteristics

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

**Table 5. Maximum Allowed Overshoot During Transitions** 

Symbol	Description	Condition (V)	Overshoot Duration as % @ T <sub>J</sub> = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Figure 1. Stratix V Device Overshoot Duration



Page 6 Electrical Characteristics

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
t <sub>RAMP</sub>	Power cupply ramp time	Standard POR	200 μs	_	100 ms	_
	Power supply ramp time	Fast POR	200 μs	_	4 ms	_

#### Notes to Table 6:

- (1)  $V_{CCPD}$  must be 2.5 V when  $V_{CCIO}$  is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V.  $V_{CCPD}$  must be 3.0 V when  $V_{CCIO}$  is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V<sub>CCBAT</sub> to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V<sub>CCBAT</sub>. Stratix V devices will not exit POR if V<sub>CCBAT</sub> stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
$V_{\text{CCHSSI\_R}}$	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Treceiver arialog power supply (left side)		0.97	1.0	1.03	V
			1.03	1.05	1.07	

Electrical Characteristics Page 7

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
			0.82	0.85	0.88	
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	neceiver arialog power supply (right side)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
		GX, GS, GT	0.82	0.85	0.88	
V <sub>CCT_GXBL</sub>	Transmitter analog newer cupply (left side)		0.87	0.90	0.93	V
	Transmitter analog power supply (left side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
		GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCT_GXBR</sub>	Transmitter analog never supply (right side)		0.87	0.90	0.93	
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

#### Notes to Table 7:

<sup>(1)</sup> This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

<sup>(2)</sup> Refer to Table 8 to select the correct power supply level for your design.

<sup>(3)</sup> When using ATX PLLs, the supply must be 3.0 V.

<sup>(4)</sup> This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Page 10 Electrical Characteristics

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

			Calibration Accuracy				
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R <sub>S</sub>	Internal series termination with calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ $R_S$	Internal series termination with calibration (34- $\Omega$ and 40- $\Omega$ setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
$48$ - $\Omega$ , $60$ - $\Omega$ , $80$ - $\Omega$ , and $240$ - $\Omega$ R <sub>S</sub>	Internal series termination with calibration (48- $\Omega$ , 60- $\Omega$ , 80- $\Omega$ , and 240- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±15	±15	±15	±15	%
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- $\Omega$ , 30- $\Omega$ , 40- $\Omega$ , 60- $\Omega$ , and 120- $\Omega$ setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- $\Omega$ and 120- $\Omega$ R <sub>T</sub>	Internal parallel termination with calibration (60- $\Omega$ and 120- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S\_left\_shift} \end{array}$	Internal left shift series termination with calibration (25- $\Omega$ R <sub>S_left_shift</sub> setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

### Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Resistance Tolerance				
Symbol	Description	Conditions	<b>C</b> 1	C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CC10</sub> = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CC10</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%

<sup>(1)</sup> OCT calibration accuracy is valid at the time of calibration only.

Electrical Characteristics Page 13

### **Internal Weak Pull-Up Resistor**

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V <sub>CC10</sub> Conditions (V) <sup>(3)</sup>	Value <sup>(4)</sup>	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%		kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R <sub>PU</sub>	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

#### Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k $\Omega$ .
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than  $V_{\text{CCIO}}$ .
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

### I/O Standard Specifications

Table 17 through Table 22 list the input voltage ( $V_{IH}$  and  $V_{IL}$ ), output voltage ( $V_{OH}$  and  $V_{OL}$ ), and current drive characteristics ( $I_{OH}$  and  $I_{OL}$ ) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The  $V_{OL}$  and  $V_{OH}$  values are valid at the corresponding  $I_{OH}$  and  $I_{OL}$ , respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012\_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

I/O		V <sub>CCIO</sub> (V)		VII	_(V)	V <sub>IH</sub>	(V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub>	I <sub>OH</sub>
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.45	V <sub>CCIO</sub> – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	-2

Page 16 Electrical Characteristics

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O		V <sub>CCIO</sub> (V)		V <sub>DIF(I</sub>	<sub>DC)</sub> (V)		V <sub>X(AC)</sub> (V)			V <sub>CM(DC)</sub> (V	)	V <sub>DIF(AC)</sub> (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V <sub>CCIO</sub> + 0.3	_	0.5* V <sub>CCIO</sub>	_	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.3	V <sub>CCIO</sub> + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V <sub>CCIO</sub> - 0.12	0.5* V <sub>CCIO</sub>	0.5*V <sub>CCIO</sub> + 0.12	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	<sub>CIO</sub> (V)	(10)		V <sub>ID</sub> (mV) <sup>(8)</sup>			$V_{ICM(DC)}$ (V)		Vo	D (V) (	6)	V	<sub>OCM</sub> (V)	(6)
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	nsmitte						of the high-s I/O pin speci							. For
2.5 V	2.375	2.5	2.625	100	V <sub>CM</sub> =	_	0.05	D <sub>MAX</sub> ≤ 700 Mbps	1.8	0.247		0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D <sub>MAX</sub> > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_		_
RSDS (HIO) <sup>(2)</sup>	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D <sub>MAX</sub> ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)	_	_	_	300	_	_	1	D <sub>MAX</sub> > 700 Mbps	1.6	_	_	_	_	_	_

### Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed  $V_{\text{ICM}}$ ,  $V_{\text{OD}}$ , and  $V_{\text{OCM}}$  specifications for BLVDS. They depend on the system topology.
- (6) RL range:  $90 \le RL \le 110 \Omega$ .
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5  $\rm V.$

### **Power Consumption**

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus<sup>®</sup> II PowerPlay Power Analyzer feature.

Electrical Characteristics Page 17



You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Switching Characteristics Page 19

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(5)</sup>	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4		_	-0.4	_		-0.4	_	1	V
Peak-to-peak differential input voltage	_	200	_	1600	200		1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled) (3)	Dedicated reference clock pin	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1050/1000/900/850 (2)		mV
coupled) (9	RX reference clock pin	1.	.0/0.9/0	.85 <sup>(4)</sup>	1.	0/0.9/0	.85 <sup>(4)</sup>	1.	0/0.9/0	.85 <sup>(4)</sup>	V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) <sup>(20)</sup>	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120	_	_	-120	_	_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R <sub>REF</sub> (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_			_	
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Page 22 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0	_	0	_	_	0	_	_	0	_	dB
	DC Gain Setting = 1	_	2	_	_	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_	_	4		_	4	_	dB
	DC Gain Setting = 3		6		_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8		_	8		_	8	_	dB
Transmitter											
Supported I/O Standards	_				-	1.4-V ar	nd 1.5-V PC	ML			
Data rate (Standard PCS)	_	600	_	12200	600		12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85-Ω setting	_	85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%		_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting	_	150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V <sub>OCM</sub> (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V <sub>OCM</sub> (DC coupled)	_	_	650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30		160	ps
Fall time <sup>(7)</sup>	80% to 20%	30	_	160	30		160	30	_	160	ps
Intra-differential pair skew	Tx V <sub>CM</sub> = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

Switching Characteristics Page 37

Figure 6 shows the Stratix V DC gain curves for GT channels.

### Figure 6. DC Gain Curves for GT Channels

### **Transceiver Characterization**

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

Page 40 Switching Characteristics

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
<b>→</b> (3) (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> ≥ 100 MHz)	_	_	0.15	UI (p-p)
t <sub>INCCJ</sub> (3), (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175 <sup>(1)</sup>	ps (p-p)
t <sub>OUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5 <sup>(1)</sup>	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t <sub>outccj_dc</sub> (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
<b>+</b> (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTCCJ_DC</sub> <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)+	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
t <sub>OUTPJ_IO</sub> (5),	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f <sub>OUT</sub> < 100 MHz)	_	_	60	mUI (p-p)
t <sub>FOUTPJ 10</sub> (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>outccj_10</sub> (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>ғоитссу_10</sub>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}}$ < 100 MHz)	_	_	60	mUI (p-p)
t <sub>CASC_OUTPJ_DC</sub>	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
f <sub>DRIFT</sub>	Frequency drift after PFDENA is disabled for a duration of 100 $\mu s$	_	_	±10	%
dK <sub>BIT</sub>	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k <sub>VALUE</sub>	Numerator of Fraction	128	8388608	2147483648	_

Switching Characteristics Page 45

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I4	4	II.a.i.k
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f <sub>HSDR</sub> (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t <sub>x Jitter</sub> - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t <sub>x Jitter</sub> - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

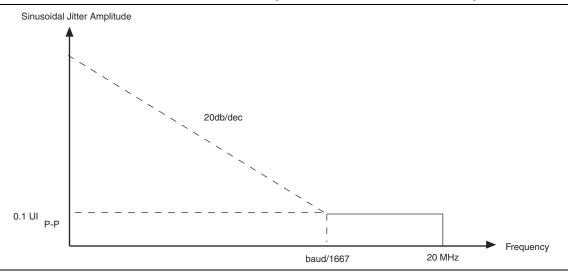
Switching Characteristics Page 49

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq$  1.25 Gbps

Jitter F	requency (Hz)	Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



### DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

### Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Configuration Specification Page 55

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Mombor		Active Serial (1)	)	Fast Passive Parallel (2)			
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	D3	4	100	0.344	32	100	0.043	
	D4	4	100	0.534	32	100	0.067	
GS	D4	4	100	0.344	32	100	0.043	
us 	D5	4	100	0.534	32	100	0.067	
	D6	4	100	0.741	32	100	0.093	
	D8	4	100	0.741	32	100	0.093	
E	E9	4	100	0.857	32	100	0.107	
	EB	4	100	0.857	32	100	0.107	

### Notes to Table 48:

### **Fast Passive Parallel Configuration Timing**

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

### DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
FPP × IO	Enabled	Disabled	4
	Enabled	Enabled	4

<sup>(1)</sup> DCLK frequency of 100 MHz using external CLKUSR.

<sup>(2)</sup> Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Page 60 Configuration Specification

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1  $^{(1)}$ 

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nconfig low to conf_done low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μS
t <sub>CF2ST1</sub>	nconfig high to nstatus high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t <sub>ST2CK</sub> (5)	nstatus high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	N-1/f <sub>DCLK</sub> <sup>(5)</sup>	_	S
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>R</sub>	Input rise time	_	40	ns
t <sub>F</sub>	Input fall time	_	40	ns
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(4)</sup>	_	_

### Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

Configuration Specification Page 63

Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	_	600	ns
t <sub>CF2ST0</sub>	nCONFIG low to nSTATUS low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	<del></del>	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(1)</sup>	μS
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nCONFIG high to first rising edge on DCLK	1,506	<del></del>	μS
t <sub>ST2CK</sub> (5)	nstatus high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	0	_	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f <sub>MAX</sub>	DCLK frequency	_	125	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μ\$
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}}$ + (8576 × CLKUSR period) $^{(4)}$	_	_

### Notes to Table 54:

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.
- (5) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

### Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximum Frequency

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles <sup>(1)</sup>
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP (2)	125 MHz	8576
DCLK	PS, FPP	125 MHz	

### Notes to Table 55:

- $(1) \quad \text{The minimum number of clock cycles required for device initialization}.$
- (2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

Glossary Page 65

Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)

Parameter	Available	Min	Fast	Model	Slow Model								
(1)	Cottings UI		Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns	
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns	
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns	
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns	

### Notes to Table 58:

- (1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.
- (2) Minimum offset does not include the intrinsic delay.

### **Programmable Output Buffer Delay**

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)

Symbol	Parameter	Typical	Unit
		0 (default)	ps
D	Rising and/or falling edge delay	25	ps
D <sub>OUTBUF</sub>		50	ps
		75	ps

### Note to Table 59:

## **Glossary**

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions		
Α				
В	_	_		
С				
D	_	_		
E	_	_		
	f <sub>HSCLK</sub>	Left and right PLL input clock frequency.		
F High-speed I/O block—Maximum and minimum LVDS data transfer ra $(f_{HSDR} = 1/TUI)$ , non-DPA.		High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.		
	f <sub>HSDRDPA</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.		

<sup>(1)</sup> You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

Glossary Page 67

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions					
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:  Bit Time  0.5 x TCCS RSKM Sampling Window (SW)  0.5 x TCCS					
S	Single-ended voltage referenced I/O standard	The JEDEC standard for <b>SSTL</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.  The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:  Single-Ended Voltage Referenced I/O Standard  VIHACO  VIHACO  VILLOCO  V					
	t <sub>C</sub>	High-speed receiver and transmitter input and output clock period.					
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\rm CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).					
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.					
Т	t <sub>DUTY</sub>	Timing Unit Interval (TUI)  The timing budget allowed for skew, propagation delays, and the data sampling window.  (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_C/w)$					
	t <sub>FALL</sub>	Signal high-to-low transition time (80-20%)					
	t <sub>INCCJ</sub>	Cycle-to-cycle jitter tolerance on the PLL clock input.					
	t <sub>OUTPJ_IO</sub>	Period jitter on the general purpose I/O driven by a PLL.					
	t <sub>OUTPJ_DC</sub>	Period jitter on the dedicated clock output driven by a PLL.					
	t <sub>RISE</sub>	Signal low-to-high transition time (20-80%)					
U	_	_					

Page 68 Glossary

### Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions		
	V <sub>CM(DC)</sub>	DC common mode input voltage.		
	V <sub>ICM</sub>	Input common mode voltage—The common mode of the differential signal at the receiver.		
	V <sub>ID</sub>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.		
	V <sub>DIF(AC)</sub>	AC differential input voltage—Minimum AC input differential voltage required for switching.		
	V <sub>DIF(DC)</sub>	DC differential input voltage— Minimum DC input differential voltage required for switching.		
	V <sub>IH</sub>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.		
	V <sub>IH(AC)</sub>	High-level AC input voltage		
	V <sub>IH(DC)</sub>	High-level DC input voltage		
V	<b>V</b> <sub>IL</sub>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.		
	V <sub>IL(AC)</sub>	Low-level AC input voltage		
	V <sub>IL(DC)</sub>	Low-level DC input voltage		
	V <sub>OCM</sub>	Output common mode voltage—The common mode of the differential signal at the transmitter.		
	<b>V</b> <sub>OD</sub>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.		
	V <sub>SWING</sub>	Differential input voltage		
	V <sub>X</sub>	Input differential cross point voltage		
	V <sub>OX</sub>	Output differential cross point voltage		
W	W	High-speed I/O block—clock boost factor		
Χ				
Υ		_		
Z				